

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Makoto Yoshino, et al.**

Art Unit (parent case): **2829**

Serial No.: **TBD**

Examiner (parent case): **Geyer, Scott B.**

Filed: **Herewith**

Docket: **TI-29448.1**

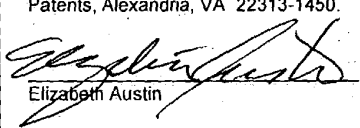
For: **Semiconductor Package Insulation
Film And Manufacturing Method
Thereof**

Conf. No.: **TBD**

PRELIMINARY AMENDMENT

Commissioner for Patents
Alexandria, VA 22313-1450

Sir:

| | |
|---|--------------------------|
| <u>MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)</u> | |
| I hereby certify that on or before this date the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450. | |
|  Elizabeth Austin | <u>7/17/2003</u> Date |

Please enter the following amendment prior to examination of the instant application.

In the Specification:

Please amend the specification by inserting before the first line the sentence:

-- This is a divisional application of Serial No. 09/909,013, filed 07/19/2001. --